

L Number	Hits	Search Text	DB	Time stamp
1	8	mold\$3 with silicon with (dry adj1 etching)	USPAT	2003/04/21 09:13
2	3	("4717893" "4793697" "5411690").PN.	USPAT	2003/04/21 09:12
3	5	5735985.URPN.	USPAT	2003/04/21 09:13
4	3170	(dry adj1 etching) same (anisotropic anad isotropic)	USPAT	2003/04/21 09:14
5	2423	(dry adj1 etching) with (anisotropic anad isotropic)	USPAT	2003/04/21 09:14
6	29	((dry adj1 etching) with (anisotropic anad isotropic)) and 385/\$.ccls.	USPAT	2003/04/21 09:15
8	4	((dry adj1 etching) with (anisotropic and isotropic)) and 385/\$.ccls.	USPAT	2003/04/21 09:15
7	317	(dry adj1 etching) with (anisotropic and isotropic)	USPAT	2003/04/21 09:22
9	1	6080988.pn.	USPAT	2003/04/21 09:48
10	19345	mold near10 resin	USPAT	2003/04/21 09:48
12	2952	(mold near10 resin) and optic\$2	USPAT	2003/04/21 09:48
13	161	((mold near10 resin) and optic\$2) and (mold near1 transfer\$3)	USPAT	2003/04/21 10:16
14	0	actuator\$1 same photolithography same sacrific\$3 same planarizing	USPAT	2003/04/21 10:18
15	140	actuator\$1 same photolithography	USPAT	2003/04/21 10:21
16	5	(actuator\$1 same photolithography) and 385/\$.ccls.	USPAT	2003/04/21 10:20
17	19799	actuator\$1 same photolithography smae sacrifice	USPAT	2003/04/21 10:21
18	1	actuator\$1 same photolithography same sacrifice	USPAT	2003/04/21 10:28
20	1	6156243.pn.	USPAT	2003/04/21 10:40
21	1	6156243.pn. and (mold with material)	USPAT	2003/04/21 10:41
22	1	6156243.pn. and resin	USPAT	2003/04/21 10:47
23	1	6017973.pn.	USPAT	2003/04/21 10:51
24	1	6017973.pn. and pressure	USPAT	2003/04/21 10:52
25	1	(6017973.pn. and pressure) and bubble\$1	USPAT	2003/04/21 10:52